



Innovative relaxed InGaN engineered substrates

for RGB Micro-LEDs

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- Efficient blue and green LEDs are in Nitride, red LEDs are in Phosphide
- Phosphide red LEDs are intrinsically not efficient at micrometer-scale (\leq 10 μ m)
- Nitride red microLEDs are the ideal solution
- but efficiency is limited by strain between substrate and the InGaN structure
- → need relaxed InGaN engineered substrate for strain management









1- InGaNOS: the relaxed InGaN engineered substrate

2- First red microLEDs

3- Conclusion and perspectives







PART 1

InGaNOS: the relaxed InGaN engineered substrate



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Sapphire or Si How to fabricate full InGaN structure ?

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InGaN Active Layer

Relaxed InGaN on substrate

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Current technology

Strain between Active Layer & GaN

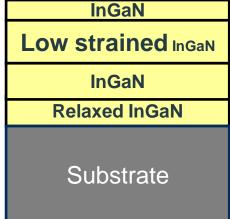
Soitec targets to reduce strain between InGaN (Active Layer) and GaN

InGaN Active LayerGaN
Strained InGaNGaN on substrateGaNSapphire or Si

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Ideal low strain structure: Full InGaN structure









Fabrication of relaxed InGaN layer

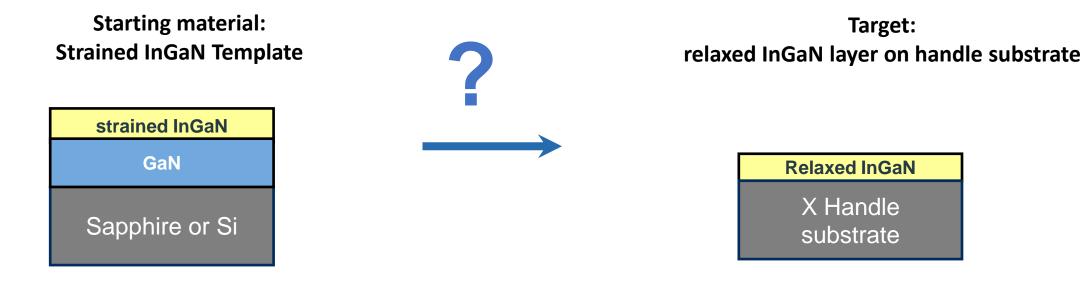


Starting material: strained InGaN Template

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Targeted substrate: relaxed InGaN layer on handle substrate



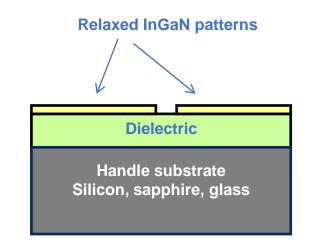






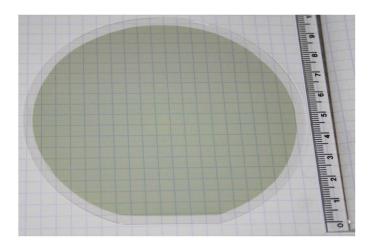
Soitec has developped relaxed InGaN substrates

- Top relaxed InGaN layer
 - Ga-face epi-ready substrate
 - Monocrystalline InGaN layer, C plane orientation
 - Pattern size: from 1x1 mm² down to 5x5 μm²
 - Lattice parameter: from 3,200 to 3,214 Å
- Dielectric layer compatible with GaN growth
- Handle substrate agnostic (Sapphire, Silicon, glass)
- Development and microLED growths are done
- on InGaN-on-Sapphire (InGaNOS)



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Structure of InGaN-on-X

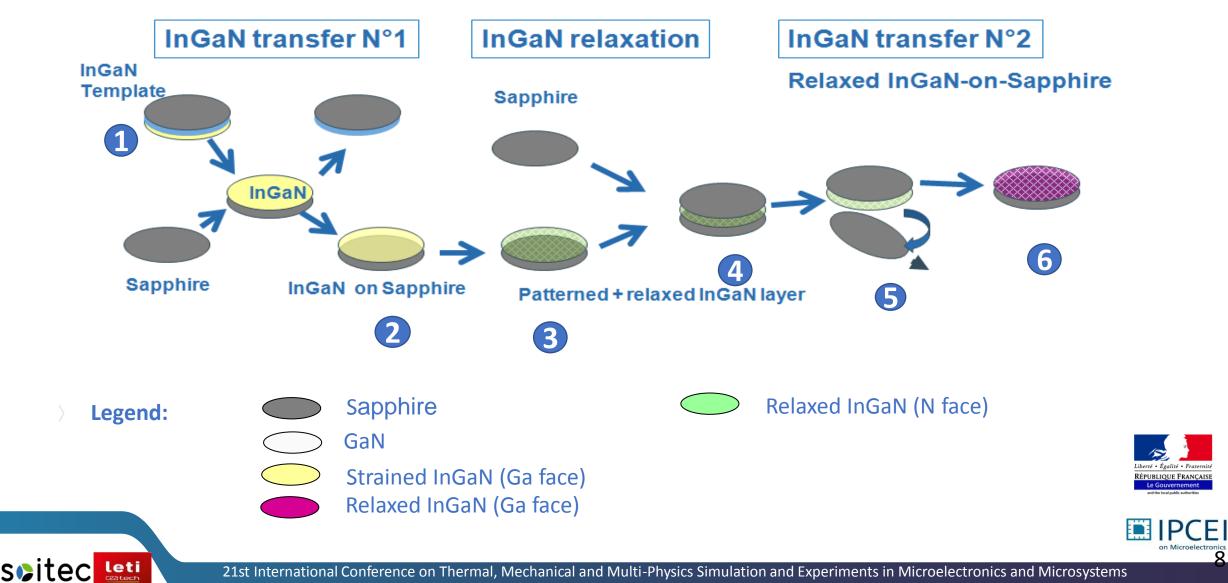






InGaNOS substrate fabrication process



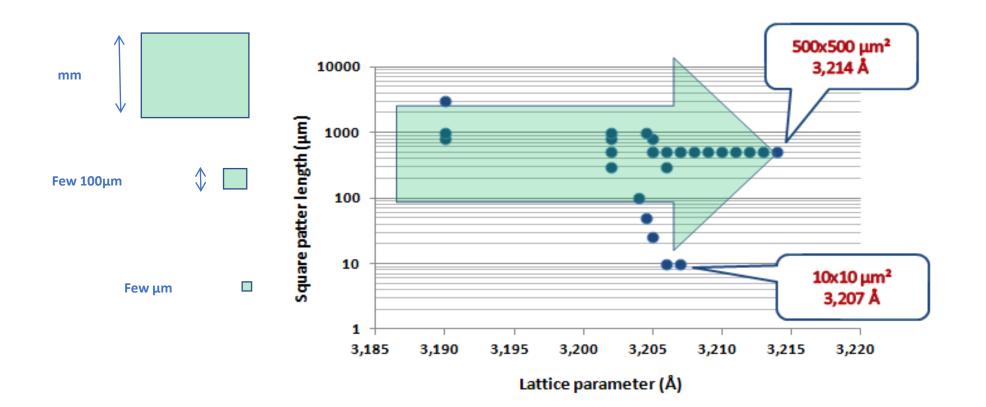


Towards high lattice parameters: 3,214 Å for 500x500 μm² patterns

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InGaNOS substrates equivalent up to 7% fully relaxed InGaN Templates





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InGaNOS proof of value at microLEDs level

• What we need to demonstrate:

Indium incorporation dependence with lattice parameter

More than 25% Indium incorporation in Quantum Wells

Demonstration of first full InGaN red microLEDs



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PART 2

First red microLEDs



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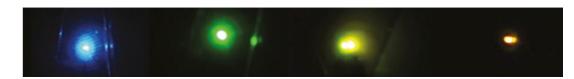
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In incorporation dependence with lattice parameter

- Co-loaded InGaNOS substrates with different lattice parameters.
- Same epi growth conditions for n-doped InGaN buffer and InGaN/ InGaN Quantums Wells

 $\mathsf{Norm}^{1.0}_{\text{n}} = \mathsf{N}^{1.0}_{\text{n}} \mathsf{N}^$

Emission wavelength tuning from blue to red



InGaNOS Lattice parameter	λ peak	FWMH
3.190 Å	482nm	33nm
3.200 Å	537nm	41nm
3.205 Å	594nm	60nm
3.205 Å	617nm	63nm



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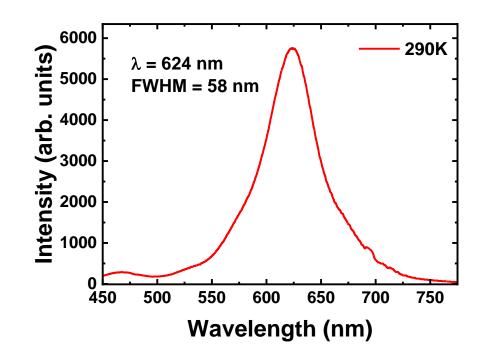
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Indium incorporation dependence with lattice parameter



6.5% red Internal quantum efficiency (IQE)

- Optimized growths conditions focused on red emission
- Central emission wavelength at 624 nm with FWHM = 58 nm at room Temperature





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6,5% IQE is at the state of the art for InGaN based planar LEDs

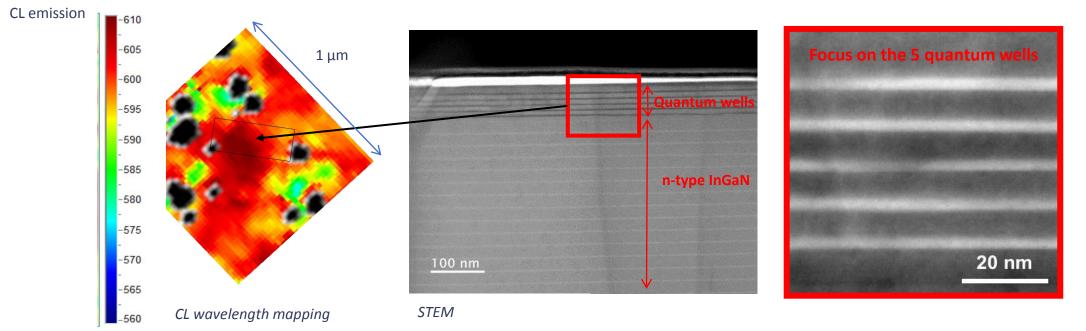


Up to 39% Indium in quantum Wells !

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Coupled characterizations between cathodoluminescence (CL) and scanning transmission electron microscopy (STEM)

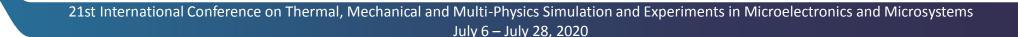


- Homogeneous Quantum Wells thickness of red emission
- 39% In content (determined by GPA analysis) vs 25% limit on std GaN substrate !



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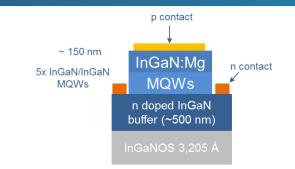
demonstration that strain release is the good option to increase In content



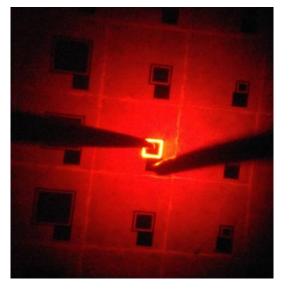
First red micro-LED

50x50 μm²

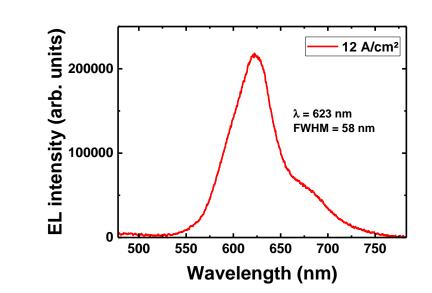




Emission @ 623 nm at 12 A/cm²



Picture from the front side Emission is from the back side





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Demonstration of first red full InGaN 50x50 µm²





PART 3

Conclusion & perspectives



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- InGaNOS enables whole visible range emission with full InGaN structures
- InGaNOS enables In content up to 40% in QWs
- Full InGaN red micro-LED is demonstrated





2 axis of development



- InGaNOS R&D line conversion in 150 mm
- 150 mm InGaNOS sampling to major LED and display makers
- Demonsration of 5% EQE red microLED



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